Lattice Semiconductor Corporation - LFSC3GA40E-7FFA1020C Datasheet

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	562
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFcBGA Rev 2 (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfsc3ga40e-7ffa1020c

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR 16x2 x 4 DPR 16x2 x 2	ROM 16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR 16x4 x 2 DPR 16x4 x 1	ROM 16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR 16x8 x 1	ROM 16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM 16x8 x1

Routing

There are many resources provided in the LatticeSC devices to route signals individually or as busses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

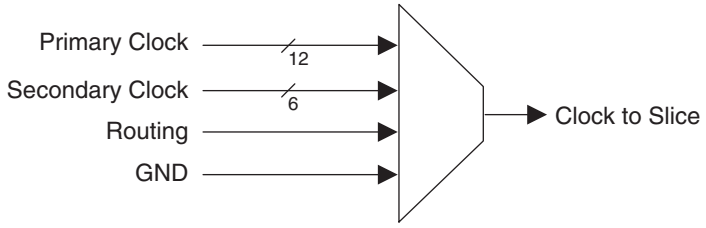
The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU) resources. The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. All connections are buffered to ensure high-speed operation even with long high-fanout connections.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Network

The LatticeSC devices have three distinct clock networks for use in distributing high-performance clocks within the device: primary clocks, secondary clocks and edge clocks. In addition to these dedicated clock networks, users are free to route clocks within the device using the general purpose routing. Figure 2-4 shows the clock resources available to each slice.

Figure 2-4. Slice Clock Selection



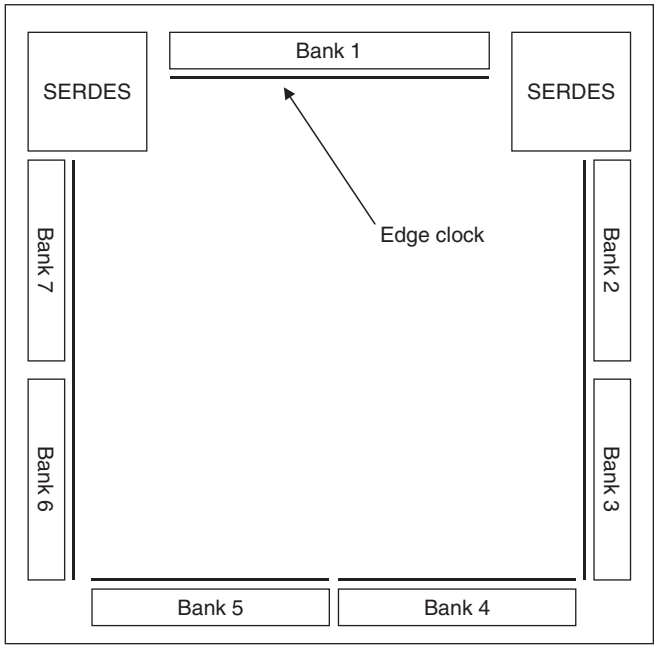
Note: GND is available to switch off the network.

Primary Clock Sources

LatticeSC devices have a wide variety of primary clock sources available. Primary clocks sources consists of the following:

- Primary clock input pins
- Edge clock input pins
- Two outputs per DLL

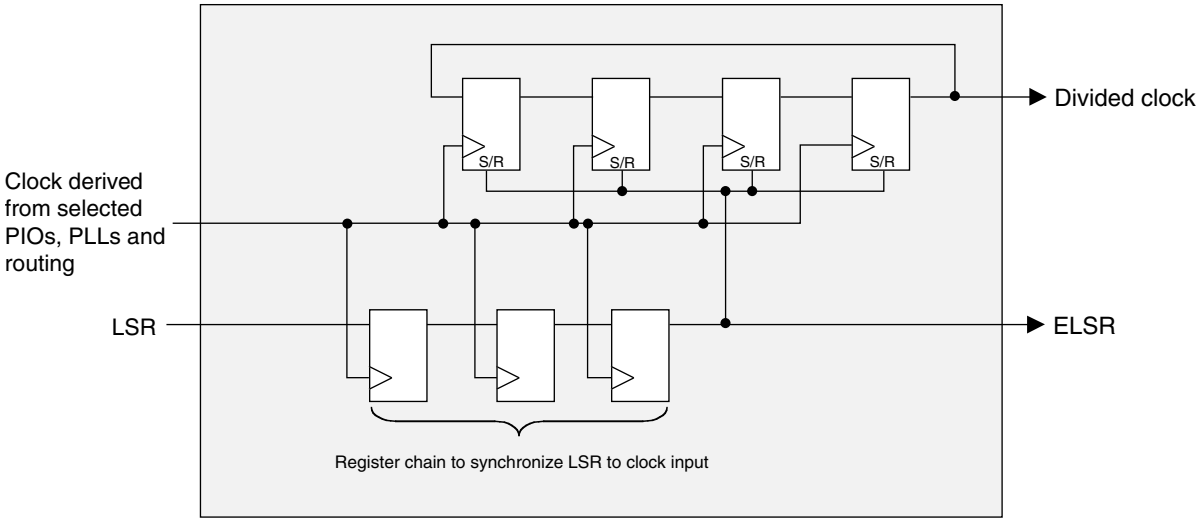
Figure 2-7. Edge Clock Resources



Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit



Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

PURESPEED I/O Buffer Banks

LatticeSC devices have seven PURESPEED I/O buffer banks; each is capable of supporting multiple I/O standards. Each PURESPEED I/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-26 shows the seven banks and their associated supplies. Table 2-7 lists the maximum number of I/Os per bank for the whole LatticeSC family.

In the LatticeSC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI33 and PCIX33) are powered using V_{CCIO}. In addition to the bank V_{CCIO} supplies, the LatticeSC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers. VCCAUX also powers a predriver of single-ended output buffers to enhance buffer performance.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeSC devices any I/O pin in a bank can be configured to be a dedicated reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Differential drivers have user selectable internal or external bias. External bias is brought in by the VREF1 pin in the bank. External bias for differential buffers is needed for applications that requires tighter than standard output common mode range.

Since a bank can have only one external bias circuit for differential drivers, LVDS and RSDS differential outputs can be mixed in a bank.

If a differential driver is configured in a bank, one pin in that bank becomes a DIFFR pin. This DIFFR pin must be connected to ground via an external 1K +/-1% ohm resistor. Note that differential drivers are not supported in banks 1, 4 and 5.

In addition, there are dedicated Terminating Supply (V_{TT}) pins to be used as terminating voltage for one of the two ways to perform parallel terminations. These V_{TT} pins are available in banks 2-7, these pins are not available in some packages. When VTT termination is not required, or used to provide the common mode termination voltage (VCMT), these pins can be left unconnected on the device. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.

There are further restrictions on the use of V_{TT} pins, for additional details refer to technical information at the end of this data sheet.

LatticeSC/M Family Data Sheet DC and Switching Characteristics

December 2011 **Data Sheet DS1004**

Absolute Maximum Ratings

Supply Voltage V_{CC}, V_{CC12}, V_{DDIB}, V_{DDOB} . . . . . -0.5 to 1.6V

Supply Voltage V_{CCAUX}, V_{DDAX25}, V_{TT} . . . . . -0.5 to 2.75V

Supply Voltage V_{CCJ} . . . . . -0.5 to 3.6V

Supply Voltage V_{CCIO} (Banks 1, 4, 5) . . . . . -0.5 to 3.6V

Supply Voltage V_{CCIO} (Banks 2, 3, 6, 7) . . . . . -0.5 to 2.75V

Input or I/O Tristate Voltage Applied (Banks 1, 4, 5) . . . . . -0.5 to 3.6V

Input or I/O Tristate Voltage Applied (Banks 2, 3, 6, 7) . . . . . -0.5 to 2.75V

Storage Temperature (Ambient) . . . . . -65 to 150°C

Junction Temperature Under Bias (Tj) . . . . . +125°C

Notes:

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Undershoot and overshoot of -2V to (VIHMAX +2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}[5]	Core Supply Voltage (Nominal 1.2V Operation)	0.95	1.26	V
V_{CCAUX}[6]	Programmable I/O Auxiliary Supply Voltage	2.375	2.625	V
V_{CCIO}[1, 2, 5, 6]	Programmable I/O Driver Supply Voltage (Banks 1, 4, 5)	1.14	3.45	V
V_{CCIO}[1, 2, 5, 6]	Programmable I/O Driver Supply Voltage (Banks 2, 3, 6, 7)	1.14	2.625	V
V_{CC12}[4, 5]	Internal 1.2V Power Supply Voltage for Configuration Logic and FPGA PLL, SERDES PLL Power Supply Voltage and SERDES Analog Supply Voltage	1.14	1.26	V
V_{DDIB}	SERDES Input Buffer Supply Voltage	1.14	1.575	V
V_{DDOB}	SERDES Output Buffer Supply Voltage	1.14	1.575	V
V_{DDAX25}	SERDES Termination Auxiliary Supply Voltage	2.375	2.625	V
V_{CCJ}[1, 5]	Supply Voltage for IEEE 1149.1 Test Access Port	1.71	3.45	V
V_{TT}[2, 3]	Programmable I/O Termination Power Supply	0.5	V_{CCAUX} - 0.5	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	+85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	105	C

1. If V_{CCIO} or V_{CCJ} is set to 2.5V, they must be connected to the same power supply as V_{CCAUX}.
2. See recommended voltages by I/O standard in subsequent table.
3. When V_{TT} termination is not required, or used to provide the common mode termination voltage (V_{CMT}), these pins can be left unconnected on the device.
4. V_{CC12} cannot be lower than V_{CC} at any time. For 1.2V operation, it is recommended that the V_{CC} and V_{CC12} supplies be tied together with proper noise decoupling between the digital VCC and analog VCC12 supplies.
5. V_{CC}, V_{CCIO} (all banks), V_{CC12} and V_{CCJ} must reach their minimum values before configuration will proceed.
6. If V_{CCIO} for a bank is nominally 1.2V/1.5V/1.8V, then V_{CCAUX} must always be higher than V_{CCIO} during power up.

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	0.024	-0.106	0.019	-0.004	0.016	0.099	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive	0.074	-0.134	0.08	-0.022	0.088	0.089	ns
LVCMOS18_OD	LVCMOS 1.8 open drain	0.002	-0.206	0	-0.196	-0.002	-0.221	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	-0.344	-0.164	-0.379	-0.186	-0.412	-0.209	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	-0.125	-0.137	-0.145	-0.157	-0.164	-0.176	ns
LVCMOS15_12mA	LVCMOS 1.5 12mA drive	-0.027	-0.166	-0.043	-0.07	-0.059	0.026	ns
LVCMOS15_16mA	LVCMOS 1.5 16mA drive	0.025	-0.195	0.013	-0.089	0.003	0.017	ns
LVCMOS15_OD	LVCMOS 1.5 open drain	-0.047	-0.267	-0.067	-0.267	-0.087	-0.299	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	-0.473	-0.293	-0.505	-0.317	-0.537	-0.34	ns
LVCMOS12_4mA	LVCMOS 1.2 4mA drive	-0.218	-0.239	-0.25	-0.271	-0.28	-0.303	ns
LVCMOS12_8mA	LVCMOS 1.2 8mA drive	-0.109	-0.269	-0.143	-0.181	-0.176	-0.093	ns
LVCMOS12_12mA	LVCMOS 1.2 12mA drive	-0.054	-0.3	-0.085	-0.203	-0.114	-0.106	ns
LVCMOS12_OD	LVCMOS 1.2 open drain	-0.126	-0.371	-0.166	-0.398	-0.204	-0.43	ns
PCI33	PCI	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX33	PCI-X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
PCIX15	PCI-X 1.5	0.208	0.227	0.233	0.312	0.259	0.398	ns
AGP1X33	AGP-1X 3.3	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns
AGP2X33	AGP-2X	-0.216	-0.791	-0.417	-1.263	-0.618	-1.735	ns

Signal Descriptions (Cont.)

Signal Name	I/O	Description
D[n:0]	I/O	In parallel configuration modes, D[7:0] receives configuration data, and each pin is pull-up enabled. For slave serial mode, D0 is the data input. D[7:3] is the output internal status for peripheral mode when RDN is low. D[7:0] is also the first byte of MPI data pins. In MPI configuration mode, MPI selectable data bus width from 8 and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
DP[m:0]	I/O	MPI selectable parity data bus width from 1, 2, and 3-bit DP[0] for D[7:0], DP[1] for D[15:8], and DP[2] for D[23:16].
BUSYN/RCLK/SCK	O	During configuration in peripheral mode, high on BUSYN indicates another byte can be written to the FPGA. If a read operation is done when the device is selected, the same status is also available on D[7] in asynchronous peripheral mode. During configuration in slave parallel mode, low on BUSYN inhibits the external host from sending new data. The output is used by slave parallel and master serial modes only for decompression. During configuration in master parallel and master byte modes, RCLK is a read clock output signal to an external memory. The RCLK frequency is the same as CCLK when used with uncompressed bitstreams. RCLK will be 1/8 the frequency of CCLK when the bitstream is compressed. During configuration in SPI modes, SCK is generated by the device and connected to the CLK input of the FLASH memory.
MPI Interface (Dedicated pin)		
MPI_IRQ_N	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
MPI Interface (User I/O if MPI is not used.)		
MPI_CS0N MPI_CS1	I	MPI chip select pins, active low on MPI_CS0N while active high on MPI_CS1. Both have to be active during the whole transfer data phase. During transfer address phase, both can be inactive so that the decoding for them from address can be slow. If they are active during address phase, one cycle can be saved for sync read.
MPI_CLK	I	This is the PowerPC bus clock. It can be a source of the clock for embedded system bus. If MPI_CLK is used as system bus clock, MPI will be set into sync mode by default. All of the operation on PowerPC side of MPI are synchronized to the rising edge of this clock.
MPI_TSIZ[1:0]	I	Driven by a bus master to indicate the data transfer size for the transaction. 01 for byte, 10 for half-word, and 00 for word.
MPI_WR_N	I	Driven high indicates that a read access is in progress. Driven low indicates that a write access is in process.
MPI_BURST	I	Driven active low indicates that a burst transfer is in progress. Driven high indicates that the current transfer is not a burst.
MPI_BDIP	I	Active low “Burst Data in Process” is driven by a PowerPC processor. Asserted indicates that the second beat in front of the current one is requested by the master. Negated before the burst transfer ends to abort the burst data phase.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESP_[ULC/URC]	—	Calibration resistor to be placed between this pin and either ground or RESPN_[ULC/URC]. RESPN_[ULC/URC] is available on select packages. If available, connection of calibration resistor between RESP_[ULC/URC] and RESPN_[ULC/URC] takes precedence over connection of calibration resistor between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
RESPN_[ULC/URC]	—	Available on selected packages. If available, calibration resistor should be placed between RESP_[ULC/URC] and RESPN_[ULC/URC] instead of between RESP_[ULC/URC] and ground. Note: only one per side of the device. Value: 4.02K ohm +/- 1% ohm.
[A:D]_VDDIBx_[L/R]	—	Input buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDOBx_[L/R]	—	Output buffer power supply for channel x (1.2V/1.5V) on left [L] or right [R] side of device.
[A:D]_VDDAX25_[L/R]	—	Auxiliary power for input and output termination (2.5V) on left [L] or right [R] side of device.

1. The ispLEVER software tools may specify VDDRX, VDDTX, VDDP and VCCL pins. These pins should be considered VCC12 pins.
Note: Signals listed as Signal A / Signal B define the same physical pin that is used for different functions based on configuration mode.

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2]

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
E4	A_VDDAX25_L	-	
B1	A_REFCLKP_L	-	
C1	A_REFCLKN_L	-	
D2	RESP_ULC	-	
F5	RESETN	1	
D1	DONE	1	
E1	INITN	1	
E2	M0	1	
E3	M1	1	
E5	M2	1	
E6	M3	1	
F2	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
F1	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
F3	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G1	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
G4	PL18D	7	VREF2_7
H3	PL22A	7	
H2	PL22B	7	
H5	PL22C	7	VREF1_7
G5	PL22D	7	DIFFR_7
H1	PL23A	7	PCLKT7_1
J1	PL23B	7	PCLKC7_1
J2	PL24A	7	PCLKT7_0
J3	PL24B	7	PCLKC7_0
H4	PL24C	7	PCLKT7_2
H6	PL24D	7	PCLKC7_2
J4	PL26A	6	PCLKT6_0
K5	PL26B	6	PCLKC6_0
J5	PL26C	6	PCLKT6_1
J6	PL26D	6	PCLKC6_1
K1	PL28A	6	
L1	PL28B	6	
L4	PL28C	6	PCLKT6_2
K4	PL28D	6	PCLKC6_2
L2	PL31C	6	VREF1_6
L3	PL35A	6	
M3	PL35B	6	
M2	PL35D	6	DIFFR_6
M1	PL37A	6	
N1	PL37B	6	
P2	PL41D	6	VREF2_6
M5	PL43A	6	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
N3	PL27A	6		PL30A	6	
P3	PL27B	6		PL30B	6	
P4	PL27C	6	PCLKT6_3	PL30C	6	PCLKT6_3
P2	PL28A	6		PL31A	6	
R2	PL28B	6		PL31B	6	
T3	PL28C	6	PCLKT6_2	PL31C	6	PCLKT6_2
R3	PL28D	6	PCLKC6_2	PL31D	6	PCLKC6_2
P1	PL31A	6		PL34A	6	
R1	PL31B	6		PL34B	6	
R5	PL31C	6	VREF1_6	PL34C	6	VREF1_6
R4	PL31D	6		PL34D	6	
T2	PL32A	6		PL35A	6	
U2	PL32B	6		PL35B	6	
T1	PL33A	6		PL38A	6	
U1	PL33B	6		PL38B	6	
V1	PL35A	6		PL42A	6	
W1	PL35B	6		PL42B	6	
V6	PL35D	6	DIFFR_6	PL42D	6	DIFFR_6
V2	PL36A	6		PL43A	6	
W2	PL36B	6		PL43B	6	
Y1	PL37A	6		PL44A	6	
AA1	PL37B	6		PL44B	6	
AB1	PL39A	6		PL48A	6	
AC1	PL39B	6		PL48B	6	
Y5	PL40A	6		PL49A	6	
Y6	PL40B	6		PL49B	6	
AD2	PL41A	6		PL51A	6	
AE2	PL41B	6		PL51B	6	
AB5	PL41D	6	VREF2_6	PL51D	6	VREF2_6
AC3	PL43A	6		PL52A	6	
AD3	PL43B	6		PL52B	6	
AF1	PL44A	6		PL55A	6	
AG1	PL44B	6		PL55B	6	
AB6	PL44C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F	PL55C	6	LLC_DLLT_IN_E/LLC_DLLT_FB_F
AC5	PL44D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F	PL55D	6	LLC_DLLC_IN_E/LLC_DLLC_FB_F
AF2	PL45A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E	PL57A	6	LLC_DLLT_IN_F/LLC_DLLT_FB_E
AG2	PL45B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E	PL57B	6	LLC_DLLC_IN_F/LLC_DLLC_FB_E
AC6	PL45C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A	PL57C	6	LLC_PLLT_IN_B/LLC_PLLT_FB_A
AC7	PL45D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A	PL57D	6	LLC_PLLC_IN_B/LLC_PLLC_FB_A
AE4	XRES	-		XRES	-	
AG4	VCC12	-		VCC12	-	
AD5	TEMP	6		TEMP	6	
AF5	VCC12	-		VCC12	-	
AH1	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B	PB3A	5	LLC_PLLT_IN_A/LLC_PLLT_FB_B
AJ1	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y9	VCCIO6	-		VCCIO6	-	
J7	VCCIO7	-		VCCIO7	-	
J8	VCCIO7	-		VCCIO7	-	
K7	VCCIO7	-		VCCIO7	-	
K8	VCCIO7	-		VCCIO7	-	
L8	VCCIO7	-		VCCIO7	-	
L9	VCCIO7	-		VCCIO7	-	
M9	VCCIO7	-		VCCIO7	-	
N9	VCCIO7	-		VCCIO7	-	
P9	VCCIO7	-		VCCIO7	-	
R9	VCCIO7	-		VCCIO7	-	
A1	GND	-		GND	-	
A30	GND	-		GND	-	
AA15	GND	-		GND	-	
AA16	GND	-		GND	-	
AK1	GND	-		GND	-	
AK30	GND	-		GND	-	
K15	GND	-		GND	-	
K16	GND	-		GND	-	
L11	GND	-		GND	-	
L12	GND	-		GND	-	
L13	GND	-		GND	-	
L14	GND	-		GND	-	
L15	GND	-		GND	-	
L16	GND	-		GND	-	
L17	GND	-		GND	-	
L18	GND	-		GND	-	
L19	GND	-		GND	-	
L20	GND	-		GND	-	
M11	GND	-		GND	-	
M12	GND	-		GND	-	
M13	GND	-		GND	-	
M14	GND	-		GND	-	
M15	GND	-		GND	-	
M16	GND	-		GND	-	
M17	GND	-		GND	-	
M18	GND	-		GND	-	
M19	GND	-		GND	-	
M20	GND	-		GND	-	
N11	GND	-		GND	-	
N12	GND	-		GND	-	
N13	GND	-		GND	-	
N14	GND	-		GND	-	
N15	GND	-		GND	-	
N16	GND	-		GND	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P32	PL30A	6		PL39A	6	
P31	PL30B	6		PL39B	6	
R28	PL30C	6	PCLKT6_3	PL39C	6	PCLKT6_3
T28	PL30D	6	PCLKC6_3	PL39D	6	PCLKC6_3
R30	PL31A	6		PL40A	6	
R29	PL31B	6		PL40B	6	
T25	PL31C	6	PCLKT6_2	PL40C	6	PCLKT6_2
T26	PL31D	6	PCLKC6_2	PL40D	6	PCLKC6_2
R31	PL34A	6		PL43A	6	
R32	PL34B	6		PL43B	6	
U23	PL34C	6	VREF1_6	PL43C	6	VREF1_6
U24	PL34D	6		PL43D	6	
T31	PL35A	6		PL44A	6	
T32	PL35B	6		PL44B	6	
T27	PL35C	6		PL44C	6	
U28	PL35D	6		PL44D	6	
U32	PL36A	6		PL45A	6	
U31	PL36B	6		PL45B	6	
U26	PL36C	6		PL45C	6	
U25	PL36D	6		PL45D	6	
V32	PL38A	6		PL47A	6	
V31	PL38B	6		PL47B	6	
V24	PL38C	6		PL47C	6	
V23	PL38D	6		PL47D	6	
V29	PL39A	6		PL48A	6	
V30	PL39B	6		PL48B	6	
U27	PL39C	6		PL48C	6	
V28	PL39D	6		PL48D	6	
W30	PL40A	6		PL49A	6	
W29	PL40B	6		PL49B	6	
V25	PL40C	6		PL49C	6	
W26	PL40D	6		PL49D	6	
W31	PL42A	6		PL51A	6	
Y31	PL42B	6		PL51B	6	
W27	PL42C	6		PL51C	6	
Y27	PL42D	6	DIFFR_6	PL51D	6	DIFFR_6
W28	PL43A	6		PL52A	6	
Y28	PL43B	6		PL52B	6	
Y26	PL43C	6		PL52C	6	
W25	PL43D	6		PL52D	6	
W32	PL44A	6		PL53A	6	
Y32	PL44B	6		PL53B	6	
AB28	PL44C	6		PL53C	6	
AA28	PL44D	6		PL53D	6	
AB32	PL47A	6		PL60A	6	
AA32	PL47B	6		PL60B	6	
AB27	PL47C	6		PL60C	6	
AC27	PL47D	6		PL60D	6	
AD31	PL48A	6		PL61A	6	
AC31	PL48B	6		PL61B	6	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AA21	VCCAUX	-		VCCAUX	-	
AA22	VCCAUX	-		VCCAUX	-	
AB11	VCCAUX	-		VCCAUX	-	
AB12	VCCAUX	-		VCCAUX	-	
AB15	VCCAUX	-		VCCAUX	-	
AB16	VCCAUX	-		VCCAUX	-	
AB17	VCCAUX	-		VCCAUX	-	
AB18	VCCAUX	-		VCCAUX	-	
AB21	VCCAUX	-		VCCAUX	-	
AB22	VCCAUX	-		VCCAUX	-	
L11	VCCAUX	-		VCCAUX	-	
L12	VCCAUX	-		VCCAUX	-	
L14	VCCAUX	-		VCCAUX	-	
L15	VCCAUX	-		VCCAUX	-	
L18	VCCAUX	-		VCCAUX	-	
L19	VCCAUX	-		VCCAUX	-	
L21	VCCAUX	-		VCCAUX	-	
L22	VCCAUX	-		VCCAUX	-	
M11	VCCAUX	-		VCCAUX	-	
M12	VCCAUX	-		VCCAUX	-	
M21	VCCAUX	-		VCCAUX	-	
M22	VCCAUX	-		VCCAUX	-	
P11	VCCAUX	-		VCCAUX	-	
P22	VCCAUX	-		VCCAUX	-	
R11	VCCAUX	-		VCCAUX	-	
R22	VCCAUX	-		VCCAUX	-	
V11	VCCAUX	-		VCCAUX	-	
V22	VCCAUX	-		VCCAUX	-	
W11	VCCAUX	-		VCCAUX	-	
W22	VCCAUX	-		VCCAUX	-	
N11	VTT_2	2		VTT_2	2	
R10	VTT_2	2		VTT_2	2	
T11	VTT_3	3		VTT_3	3	
U11	VTT_3	3		VTT_3	3	
Y11	VTT_3	3		VTT_3	3	
AB13	VTT_4	4		VTT_4	4	
AB14	VTT_4	4		VTT_4	4	
AC15	VTT_4	4		VTT_4	4	
AB19	VTT_5	5		VTT_5	5	
AB20	VTT_5	5		VTT_5	5	
AC18	VTT_5	5		VTT_5	5	
T22	VTT_6	6		VTT_6	6	
U22	VTT_6	6		VTT_6	6	
Y22	VTT_6	6		VTT_6	6	
N22	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
M17	VCC12	-		VCC12	-	
M16	VCC12	-		VCC12	-	
T12	VCC12	-		VCC12	-	
T21	VCC12	-		VCC12	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
V25	PL44C	6		PL56C	6	
W25	PL44D	6		PL56D	6	
U34	PL45A	6		PL57A	6	
V34	PL45B	6		PL57B	6	
V26	PL45C	6		PL57C	6	
W26	PL45D	6		PL57D	6	
V33	PL47A	6		PL60A	6	
W33	PL47B	6		PL60B	6	
V24	PL47C	6		PL60C	6	
W24	PL47D	6		PL60D	6	
W31	PL48A	6		PL63A	6	
Y31	PL48B	6		PL63B	6	
Y29	PL48C	6		PL63C	6	
AA29	PL48D	6		PL63D	6	
Y33	PL49A	6		PL65A	6	
AA33	PL49B	6		PL65B	6	
Y28	PL49C	6		PL65C	6	
AA28	PL49D	6		PL65D	6	
AB32	PL51A	6		PL76A	6	
AC32	PL51B	6		PL76B	6	
AA26	PL51C	6		PL76C	6	
AA27	PL51D	6	DIFFR_6	PL76D	6	DIFFR_6
AB31	PL52A	6		PL77A	6	
AC31	PL52B	6		PL77B	6	
Y24	PL52C	6		PL77C	6	
AA24	PL52D	6		PL77D	6	
AE34	PL53A	6		PL78A	6	
AF34	PL53B	6		PL78B	6	
AB30	PL53C	6		PL78C	6	
AC30	PL53D	6		PL78D	6	
AD33	PL56A	6		PL80A	6	
AE33	PL56B	6		PL80B	6	
AD30	PL56C	6		PL80C	6	
AE30	PL56D	6		PL80D	6	
AE32	PL57A	6		PL81A	6	
AF32	PL57B	6		PL81B	6	
AA25	PL57C	6		PL81C	6	
AB25	PL57D	6		PL81D	6	
AJ34	PL58A	6		PL82A	6	
AK34	PL58B	6		PL82B	6	
AB27	PL58C	6		PL82C	6	
AC27	PL58D	6		PL82D	6	
AF33	PL60A	6		PL84A	6	
AG33	PL60B	6		PL84B	6	
AC29	PL60C	6		PL84C	6	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).
2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
N27	PL47C	7	
P27	PL47D	7	
K33	PL49A	7	
L33	PL49B	7	
M30	PL49C	7	
N30	PL49D	7	
M31	PL51A	7	
N31	PL51B	7	
P24	PL51C	7	
R24	PL51D	7	
M33	PL56A	7	
N33	PL56B	7	
U25	PL56C	7	
T25	PL56D	7	
L34	PL57A	7	
M34	PL57B	7	
P29	PL57C	7	
R29	PL57D	7	
N34	PL60A	7	
P34	PL60B	7	
R27	PL60C	7	
T27	PL60D	7	
R32	PL61A	7	PCLKT7_1
R31	PL61B	7	PCLKC7_1
U24	PL61C	7	PCLKT7_3
T24	PL61D	7	PCLKC7_3
P33	PL62A	7	PCLKT7_0
R33	PL62B	7	PCLKC7_0
T26	PL62C	7	PCLKT7_2
U26	PL62D	7	PCLKC7_2
T32	PL64A	6	PCLKT6_0
T31	PL64B	6	PCLKC6_0
U29	PL64C	6	PCLKT6_1
V29	PL64D	6	PCLKC6_1
T30	PL65A	6	
U30	PL65B	6	
U27	PL65C	6	PCLKT6_3
V27	PL65D	6	PCLKC6_3
R34	PL66A	6	
T34	PL66B	6	
U28	PL66C	6	PCLKT6_2
V28	PL66D	6	PCLKC6_2
V30	PL69A	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AM27	GND	-		GND	-	
AM36	GND	-		GND	-	
AM7	GND	-		GND	-	
AP4	GND	-		GND	-	
AP40	GND	-		GND	-	
AR14	GND	-		GND	-	
AR20	GND	-		GND	-	
AR23	GND	-		GND	-	
AR29	GND	-		GND	-	
AR35	GND	-		GND	-	
AR8	GND	-		GND	-	
AT11	GND	-		GND	-	
AT17	GND	-		GND	-	
AT26	GND	-		GND	-	
AT32	GND	-		GND	-	
AU3	GND	-		GND	-	
AU39	GND	-		GND	-	
AW12	GND	-		GND	-	
AW18	GND	-		GND	-	
AW22	GND	-		GND	-	
AW28	GND	-		GND	-	
AW34	GND	-		GND	-	
AW6	GND	-		GND	-	
AY15	GND	-		GND	-	
AY21	GND	-		GND	-	
AY25	GND	-		GND	-	
AY31	GND	-		GND	-	
AY37	GND	-		GND	-	
AY9	GND	-		GND	-	
B1	GND	-		GND	-	
B42	GND	-		GND	-	
BA1	GND	-		GND	-	
BA42	GND	-		GND	-	
BB2	GND	-		GND	-	
BB41	GND	-		GND	-	
C10	GND	-		GND	-	
C12	GND	-		GND	-	
C13	GND	-		GND	-	
C16	GND	-		GND	-	
C18	GND	-		GND	-	
C19	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C27	GND	-		GND	-	
C28	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1101 - Power Estimation and Management for LatticeSC Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Date	Version	Section	Change Summary
December 2011	02.4	DC and Switching Characteristics	Updated JTAG Port Timing Specifications table.